

# 100% Material Declaration Data Sheet

## FTG256 Package for Spartan-3AN FPGAs

**Average Weight: 0.7331g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die 1</b>					<b>0.008450</b>	<b>1.153</b>
	Silicon	7440-21-3	100.00	Basis	0.008450	
<b>Silicon Die 2</b>					<b>0.002400</b>	<b>0.327</b>
	Silicon	7440-21-3	100.00	Basis	0.002400	
<b>Die Attach Adhesive 1</b>					<b>0.001998</b>	<b>0.273</b>
	Polymeric Material	Proprietary	3.00	Main Material	0.000060	
	Di-ester Resin	Proprietary	7.50	Main Material	0.000150	
	Functionalized Ester	Proprietary	3.00	Main Material	0.000060	
	Silver	7440-22-4	86.50	Main Material	0.001728	
<b>Die Attach Adhesive 2</b>					<b>0.000244</b>	<b>0.033</b>
	Silicon Dioxide	Proprietary	50.00	Main Material	0.000122	
	Di-ester Resin	Proprietary	15.00	Main Material	0.000037	
	Epoxy Resin	Proprietary	7.50	Main Material	0.000018	
	Polymeric Material	Proprietary	7.50	Main Material	0.000018	
	Polymeric Material	Proprietary	20.00	Main Material	0.000049	
<b>Mold Compound</b>					<b>0.382407</b>	<b>52.164</b>
	Silica Fused	60676-86-0	85.20	Main Material	0.325811	
	Epoxy Resin A	Trade Secret	3.00	Main Material	0.011472	
	Epoxy Resin B	Trade Secret	3.00	Main Material	0.011472	
	Phenol resin A	Trade Secret	5.00	Main Material	0.019120	
	Phenol Resin B	Trade Secret	1.50	Main Material	0.005736	
	Metal Hydroxide	Trade Secret	2.00	Main Material	0.007648	
	Carbon Black	1333-86-4	0.30	Main Material	0.001147	
<b>Gold Wire 1.0 mil</b>					<b>0.009510</b>	<b>1.297</b>
	Gold	7440-57-5	100.00	Main Material	0.009510	
<b>Gold Wire 1.1 mil</b>					<b>0.000360</b>	<b>0.049</b>
	Gold	7440-57-5	100.00	Main Material	0.000360	
<b>Solder Ball</b>					<b>0.123760</b>	<b>16.882</b>
	Tin	7440-31-5	96.50	Main Material	0.118191	
	Silver	7440-22-4	4.00	Main Material	0.004950	
	Copper	7440-50-8	0.50	Main Material	0.000619	

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Substrate					<b>0.203961</b>	<b>27.822</b>
	Copper	7440-50-8	33.37	Main Material	0.068062	
	Nickel	7440-02-0	1.05	Main Material	0.002142	
	Gold	7440-57-5	0.28	Main Material	0.000571	
	Glass Fiber	NA	13.20	Main Material	0.026923	
	Halogen FR	NA	5.80	Main Material	0.011830	
	BT (Core)	NA	33.10	Main Material	0.067511	
	Solder Mask	NA	13.20	Main Material	0.026923	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
10/22/10	1.0 Draft	Initial Xilinx release.

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